

ABSTRACT

A pre-preg sheet including a substrate and a resin impregnated in the substrate is provided. A first metal foil is placed on the pre-preg sheet to provide a laminated body. The laminated body is put in a heating device having a temperature maintained at a temperature close to a softening temperature of the resin. The laminated body is compressed at the temperature at a predetermined pressure. The first metal foil is bonded to the pre-preg sheet of the laminated body and hardening the resin, thus providing a circuit board. This method provides a stable resistance of a conductive paste filling a through-hole in the pre-preg sheet to be compressed at a small rate.